

Graphic Memory

Product Guide

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2. GRAPHIC MEMORY COMPONENT PRODUCT GUIDES

Product	Density	Banks	Part Num.	PKG & Speed	Org.	Interf.	Ref.	Voltage(V)	PKG.	PKG Type	Status
gDDR2 SDRAM	512Mb G-die	4Banks	K4N51163QG	HC20/25	32Mx16	SSTL_18	8K/64ms	1.8V ± 0.1V	84ball FBGA	Halogen-Free & Lead-Free	Mass Production
	512Mb Z-die		K4N51163QZ	HC20/25							
	1Gb E-die	8Banks	K4N1G164QE	HC20/25	64Mx16					Halogen-Free, Lead-Free & Flip-Chip	CS Jul. '10
	1Gb F-die		K4N1G164QF	BC20/25							
gDDR3 SDRAM	1Gb E-die	8Banks	K4W1G1646E	HC1A/11 12/15	64Mx16	SSTL_15	8K/64ms	1.5V ± 0.075V	96ball FBGA	Halogen-Free & Lead-Free	Mass Production
	2Gb B-die		K4W2G1646B	HC12/15	128Mx16						CS Jul. '10
	2Gb C-die		K4W2G1646C	HC1A/11 12/15	128Mx16						
GDDR3 SGRAM	512Mb I-die	8Banks	K4J52324KI	HC7A/08 1A/12/14	16Mx32	Pseudo Open_Drain	8K/32ms	1.8V ± 0.1V	136ball FBGA	Halogen-Free & Lead-Free	Mass Production
	1Gb E-die		K4J10324KE	HC7A/08 1A/12/14	32Mx32			1.8V ± 0.1V			Mass Production
GDDR5 SGRAM	1Gb E-die	8Banks	K4G10325FE	HC04/05 5C	32Mx32	POD_15	8K/32ms	1.5V ± 0.045V	170ball FBGA	Halogen-Free & Lead-Free	Mass Production
	2Gb C-die	16Banks	K4G20325FC	TBD	64Mx32	POD_15	16K/32ms	1.5V ± 0.045V	170ball FBGA	Halogen-Free & Lead-Free	CS Jun. '10